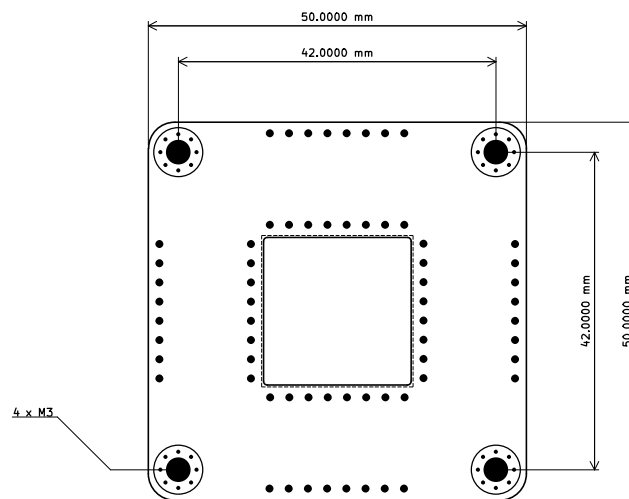


2025-02-06

EPS Module BoB v1

r1



### BOARD CHARACTERISTICS

Copper Layer Count: 2 Board Thickness: 1.6000 mm  
Board overall dimensions: 23.0000 mm x 23.0000 mm  
Min track/spacing: 0.1500 mm / 0.1500 mm Min hole diameter: 0.3000 mm  
Copper Finish: ENIG Impedance Control: No  
Castellated pads: No Plated Board Edge: No  
Edge card connectors: No

Layer Name	Type	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mm	Not specified	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Not specified	0.01 mm	White	3.3	0
F.Cu	copper		0.035 mm		1	0
Dielectric 1	core	FR4	1.51 mm	Not specified	4.5	0.02
B.Cu	copper		0.035 mm		1	0
B.Mask	Bottom Solder Mask	Not specified	0.01 mm	White	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	Not specified	1	0



Company: **Butter Robotics**  
Designer: Benny Megidish  
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URL: <https://butterrobotics.com>

Sheet:  
File: eps-module-tester-v1.kicad\_pcb


**Title: EPS Module BoB v1**

Id: 1/1

Size: A4 Date: 2025-02-06

**Rev: 1**

KiCad E.D.A. 8.0.8

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